

### **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### **Listing of Claims:**

Claim 1 (withdrawn): A manufacturing method of the high purity copper sulfate according to claim 24, including the steps of dissolving copper sulfate crystals in purified water, performing evaporative concentration thereto, removing the crystals precipitated initially, performing further evaporative concentration to effect crystallization, subjecting this to filtration to obtain high purity copper sulfate, and performing desiccation thereto.

Claim 2 (withdrawn): A manufacturing method of high purity copper sulfate according to claim 1, wherein the initial pH of the solution in which the copper sulfate was dissolved in purified water is 2 to 4, and the pH of the solution after removing the crystals precipitated initially is 2 or less.

Claims 3-19 (canceled).

Claim 20 (previously presented): A high purity copper sulfate prepared by a process comprising the steps of dissolving copper sulfate crystals in purified water, performing evaporative concentration thereto, removing the crystals precipitated initially, performing further evaporative concentration to effect crystallization, subjecting this to filtration to obtain high purity copper sulfate, and performing desiccation thereto, wherein a purity of said copper sulfate

is 99.99wt% or higher and in which a content of transition metals, such as Fe, Cr, and Ni, is 3 wtppm or less.

Claim 21 (previously presented): High purity copper sulfate according to claim 20, wherein a content of Ag and Cl in said copper sulfate is 1wtppm or less, respectively.

Claim 22 (previously presented): High purity copper sulfate according to claim 21, wherein a content of alkali metals, such as Na and K, and alkaline earth metals, such as Ca and Mg, in said copper sulfate is 1 wtppm or less, respectively.

Claim 23 (previously presented): High purity copper sulfate according to claim 22, wherein a content of an Si containing oxide in said copper sulfate is 10wtppm or less based on Si conversion.

Claim 24 (previously presented): A copper sulfate having a purity of 99.99wt% or higher.

Claim 25 (previously presented): A copper sulfate according to claim 24, wherein said copper sulfate has a content of transition metals, such as Fe, Cr, and Ni, of 3 wtppm or less.

Claim 26 (previously presented): A copper sulfate according to claim 25, wherein said copper sulfate has a content of Ag and Cl of 1wtppm or less, respectively.

Claim 27 (previously presented): A copper sulfate according to claim 26, wherein said copper sulfate has a content of alkali metals, such as Na and K, and alkaline earth metals, such as Ca and Mg, of 1 wtppm or less, respectively.

Claim 28 (previously presented): A copper sulfate according to claim 27, wherein said copper sulfate has a content of an Si containing oxide of 10wtppm or less based on Si conversion.

Claim 29 (previously presented): A copper sulfate according to claim 24, wherein said copper sulfate has a content of Ag and Cl of 1wtppm or less, respectively.

Claim 30 (previously presented): A copper sulfate according to claim 24, wherein said copper sulfate has a content of alkali metals, such as Na and K, and alkaline earth metals, such as Ca and Mg, of 1 wtppm or less, respectively.

Claim 31 (previously presented): A copper sulfate according to claim 24, wherein said copper sulfate has a content of an Si containing oxide of 10wtppm or less based on Si conversion.

Claim 32 (previously presented): An electrolytic solution for electroplating copper to form a circuit or wiring of a semiconductor device, comprising:

copper sulfate having a purity of 99.99wt% (4N) or higher;

said copper sulfate having a content of transition metals of 3wtppm or less;

said copper sulfate having a content of Ag and Cl of 1wtppm or less, respectively;

said copper sulfate having a content of alkali metals and alkaline earth metals of 1 wtppm or less, respectively; and  
said copper sulfate having a content of a Si containing oxide of 10wtppm or less based on Si conversion.

Claim 33 (currently amended): An electrolytic solution according to claim 32, wherein said copper sulfate has a content of nickel (Ni) of 1wtppm or less and wherein said copper sulfate has a content of sodium (Na) of 0.3wtppm or 0.4wtppm.

Claim 34 (currently amended): An electrolytic solution according to claim [32] 33, wherein said copper sulfate has a content of nickel (Ni) of 0.2wtppm, and wherein said copper sulfate has a purity of 99.999wt% (5N) or higher.

Claim 35 (new): A copper sulfate according to claim 27, wherein said copper sulfate has a content of sodium (Na) of 0.3wtppm or 0.4wtppm.

Claim 36 (new): High purity copper sulfate according to claim 22, wherein said copper sulfate has a content of sodium (Na) of 0.3wtppm or 0.4wtppm.